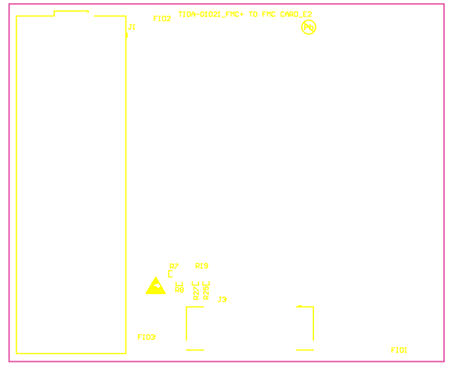
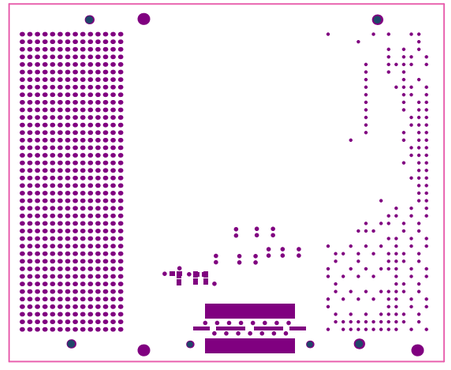
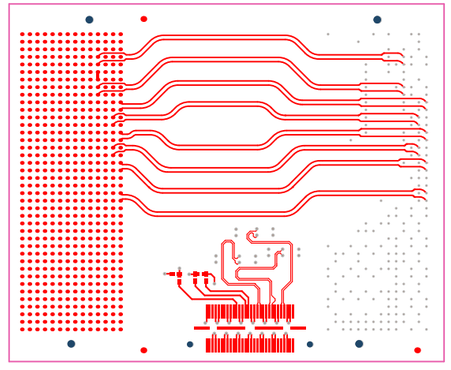


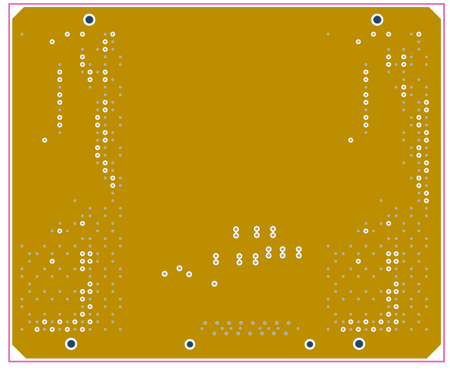
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:	
LAYER NAME = TOP OVERLAY	TID #: 01021			
PLOT NAME = Top Overlay	GENERATED : 11/09/2017 12:12:36 PM			TEXAS INSTRUMENTS



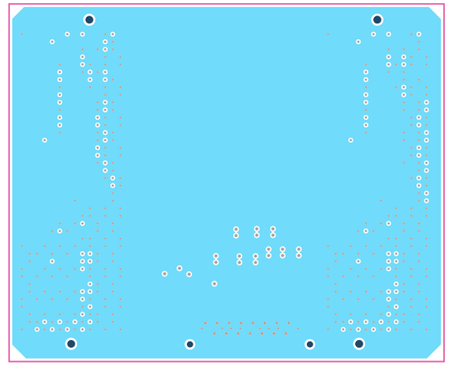
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:
LAYER NAME = TOP SOLDER	TID #: 01021		
PLOT NAME = Top Solder Mask	GENERATED : 11/09/2017 12:12:36 PM		TEXAS INSTRUMENTS



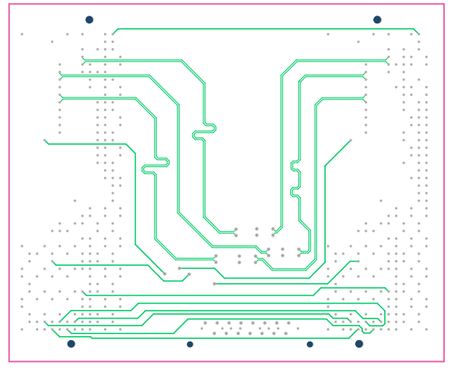
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:
LAYER NAME = Top Layer	TID #: 01021		
PLOT NAME = Top Layer	GENERATED : 11/09/2017 12:12:36 PM		TEXAS INSTRUMENTS



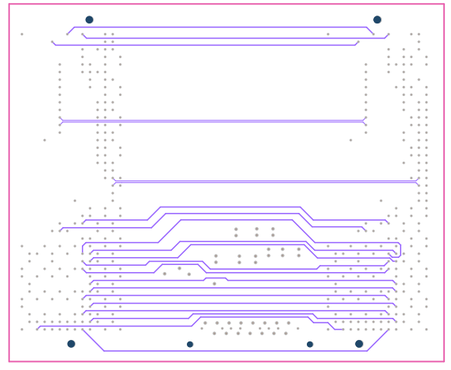
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:
LAYER NAME = GND LAYER1	TID #: 01021		
PLOT NAME = Signal Layer 1	GENERATED : 11/09/2017 12:12:36 PM		TEXAS INSTRUMENTS



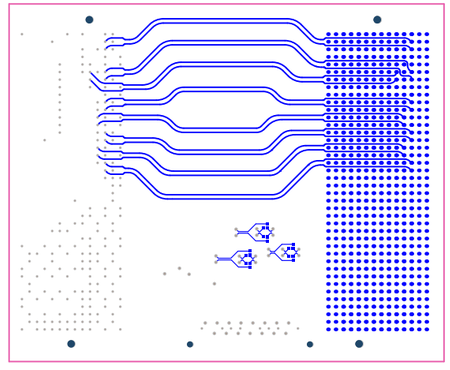
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:
LAYER NAME = GND LAYER2	TID #: 01021		
PLOT NAME = Signal Layer 2	GENERATED : 11/09/2017 12:12:36 PM		TEXAS INSTRUMENTS



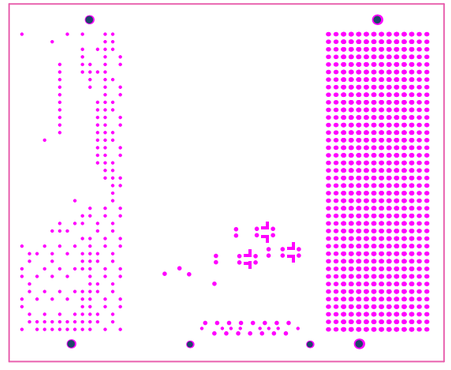
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:	
LAYER NAME = Signal Layer 1	TID #: 01021			
PLOT NAME = Signal Layer 3	GENERATED : 11/09/2017 12:12:36 PM			TEXAS INSTRUMENTS



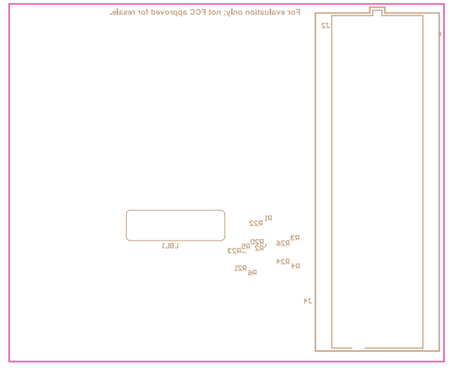
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:	
LAYER NAME = Signal Layer 2	TID #: 01021			
PLOT NAME = Signal Layer 4	GENERATED : 11/09/2017 12:12:36 PM			TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:	
LAYER NAME = BOTTOM LAYER	TID #: 01021			
PLOT NAME = Bottom Layer	GENERATED : 11/09/2017 12:12:36 PM			TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:	
LAYER NAME = BOTTOM SOLDER	TID #: 01021			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/09/2017 12:12:36 PM			TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:
LAYER NAME = BOTTOM OVERLAY	TID #: 01021		
PLOT NAME = Bottom Overlay	GENERATED : 11/09/2017 12:12:36 PM		TEXAS INSTRUMENTS

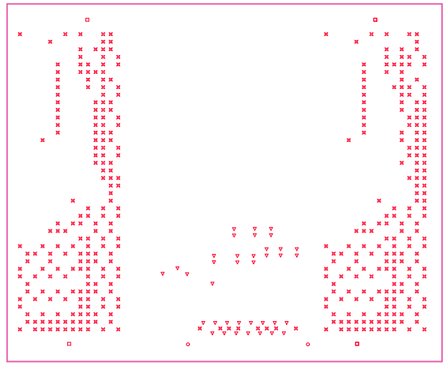
IMPEDANCE TABLE:-

Layer	50 OHM SE	100 OHM DIFF TIGHTLY COUPLED	100 OHM DIFF LOOSELY COUPLED	REFERENCE
	TRACE WIDTH (MILS) +/-10%	WIDTH/SPACING (MILS) +/-10%	WIDTH/SPACING (MILS) +/-10%	Layer
Top Layer	11mils	6mil trace/ 5mil space	10mil trace/ 18mil space	GND LAYER1
SIGNAL Layer1	8mils	5.5mil trace/ 5.5mil space		GND LAYER1
SIGNAL Layer2	8mils	5.5mil trace/ 5.5mil space		GND LAYER2
BOTTOM Layer	11mils	6mil trace/ 5mil space	10mil trace/ 18mil space	GND LAYER2

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.50mil	3.9	
3	Top Layer	Copper	2.00mil		
4	Dielectric1	R-5670K	5.80mil	3.5	
5	GND LAYER1	Copper	0.60mil		
6	Dielectric 2	R-5775K	5.00mil	3.58	
7	Signal Layer 1	Copper	0.60mil		
8	Dielectric 5	R-5775K	32.80mil	4	
9	Signal Layer 2	Copper	0.60mil		
10	Dielectric 2	R-5775K	5.00mil	3.58	
11	GND LAYER2	Copper	0.60mil		
12	Dielectric 3	R-5670K	5.80mil	3.5	
13	Bottom Layer	Copper	2.00mil		
14	Bottom Solder	Solder Resist	0.50mil	3.9	
15	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Pad Shape
○	2	40.16mil (1.020mm)	NPTH	Round	Rounded
□	6	50.00mil (1.270mm)	NPTH	Round	Rounded
▽	37	12.00mil (0.305mm)	PTH	Round	Rounded
⌑	391	8.00mil (0.203mm)	PTH	Round	Rounded
	436 Total				

FOR 12MIL DRILL +0/-12MIL
FOR 8MIL DRILL +0/-8MIL
FOR NPTH DRILL +/-2MIL



DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
73MM X 60mm

Number of Layers : 6
MIN. TRACK WIDTH: 5.5 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 18 MIL
MINIMUM ANNULAR RING 5MIL EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [ ] FR-4 High Tg [X] OTHER R-5775K , R-5670K
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.2MIL (1oz) [X] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [ ] 0.7MIL (1/2oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [ ] NO [X]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [X] NO [ ]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

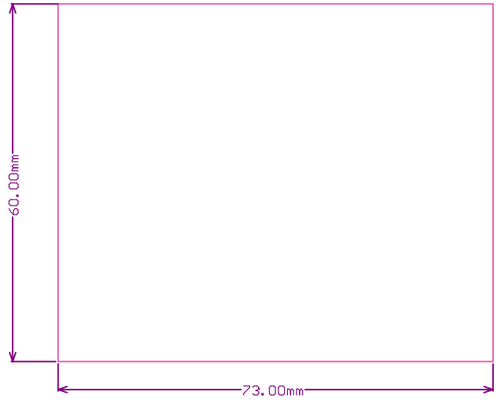
FMC+ TO FMC

DESIGNED FOR: Public Release

FILE NAME: TIDA-01021_FMC+ TO FMC Adapter Card.PcbDoc

ENGINEER: Ajeet Pal
LAYOUT BY: Avinash N
SCALE: 1.00
ALTIUM DESIGNER VERSION: 16.1.9.221

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:
LAYER NAME = DRILL DRAWING	TID #: 01021		
PLOT NAME = Drill Drawing	GENERATED : 11/09/2017 12:12:36 PM		TEXAS INSTRUMENTS



1000 (mil)

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: FMC+ TO FMC	REV: E2	SVN REV:	
LAYER NAME = M1 Board Outline	TID #: 01021			
PLOT NAME = Board Dimensions	GENERATED : 11/09/2017 12:12:36 PM			TEXAS INSTRUMENTS

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